

1. Purpose:

This is qualification test report. The purpose of this test is to evaluate the performance of Spring finger. Testing was performed on below products to determine it compliance with the requirements of product specification 108-115061-1.

2. Scope:

This is test report for Type A 1.6H connector. Testing was performed at TE Connectivity Shanghai Electrical Components Test Laboratory between Oct, 2013 and Dec, 2013.

3. Conclusion:

The product met the electrical, mechanical, and environmental performance requirements of TE product specification 108-115061-1.

4. Test samples:

Samples were taken randomly from current production. The following part numbers were used for test:

| Description | Product Part No. |
|---------------------------|------------------|
| Type A 1.6h Spring Finger | 2199248-6 |

5. Test Requirements and Procedures Summary:

5.1 Examination:

| Test Description | Requirement | Procedures |
|-------------------------------|---|--|
| Visual examination of product | Meets requirements of product drawing and applicable instructions on customer drawing, and application specification. | Visual, dimensional and functional per applicable inspection plan. In according with IEC 60512-1-1 Magnification 10x |

5.2 Electrical

| Test Description | Requirement | Procedures |
|-------------------------------------|--|---|
| Low level contact resistance (LLCR) | 75m Ω Max (Initial), 100m Ω Max (Final) | Subject mated connector to 20mV Max. open circuit at 100mA. Need to exclude wire resistance from measurement. (see 108-115061-1, Fig.2) Per EIA 364-23 |
| Temperature rise | After tests maximum increase of contact temperature, 30°C max. | Measured at maximum rated current. Per EIA 364-70, Method 2 |

5.3 Environmental

| Test Description | Requirement | Procedures |
|--|--|--|
| Damp heat | No change to performance Contact resistance: Max. 50mOhm for Cu alloy / 100mOhm for SST Measure the resistance without opening the mating after test. | Temp 25-55 °C, RH 90-100% for 18 cycles of 24 hours each. The typical cycle in temp 25°C -> 55°C in 3 hours then maintain at 55°C for 9 hours Temp +55°C -> +25°C in 3 hours, maintain at 25°C for 9 hours. Recovery at 25°C. R/H 75% for 2 hours Mated tests: 10 mA (voltage is defined by current and resistance) IEC 60068-2-30 Db |
| Vibration | No mechanical damage. No change to performance. Discontinuity <1us Max. 50mOhm | Frequency: 10 - 100 Hz: 3 m2/s3 100 - 500 Hz: -3dB/Oct. for: 3 x 60 min (X- Y- and Z-axis) in minimum deflection position. IEC60068-2-64Fh |
| Shock | No mechanical damage. No change to performance. Discontinuity<1us Max. 50mOhm | Pulse shape half sine, peak acceleration 50 G, pulse 11 ms, 3 shocks in both directions in XYZ axis IEC60068-2-27Ea |
| Nitric Acid Vapour test | Requirements: see Document ID: DTY11017- EN-2.0. | 2 Hours 69±2 % concentration acid Acc. Document ID: DTY11017-EN- 2.0: Guideline for porosity testing of gold coated metallic connector springs – Nitric acid vapour test Blank cutting edges have to be sealed. IEC 600068-2-78 |
| Solderability | Soldering area shall have a minimum of 95% solder coverage. | 245±3°C, for 2-3 seconds, |
| Resistance to reflow soldering heat | No cosmetic damage and shall meet requirement of subsequent test. | Test with reflow profile for soldering heat resistance described in Figure 1 through oven 3 times. |
| thermal shock | No change to performance Contact resistance: Max. 50mOhm for Cu alloy / 100mOhm for SST Normal Force performance. | -40° /+85° C, transition time 5 minutes max, 25 cycles. Duration time: 30 minutes. Recovery: 2 hours at 25° C, RH 75%. In accordance with IEC 68-2-14-N. (Nokia STR 1H2013, paragraph 3.3) |

5.4 Mechanical

| Test Description | Requirement | Procedures |
|--|---|---|
| Contact force at maximum working height (minimum deflection) low force scalable family | 0.2N Min. | Compress spring to max. Working height to PWB surface. Force must be measured from return curve. Spring force-deflection curve described. Have to be fulfilled after 3 reflow cycles. |
| Contact force at minimum working height (maximum deflection) low force scalable family | 1N + 20% Max. | Compress spring to max. Working height to PWB surface. Force must be measured from return curve. Spring force-deflection curve described. Have to be fulfilled after 3 reflow cycles. |
| Durability (Life cycle) Low Force Scalable Family | No functional damage Contact resistance : 50mΩ Max. Normal force should meet spec | 1x max working range + 5000 x 50% working range Mate contact at max.20 matings per minute to 5000 cycles with rigid actuator shaft. Vertical direction deflection to a 1/2 of working height. |
| Durability (Spring dynamic test) Low Force Scalable Family | No functional damage Contact resistance : 50mΩ Max. Normal force should meet spec | 1x max working range + 10000 x 50% working range Mate contact at max.20 matings per minute to 10000 cycles with rigid actuator shaft. Cycles for Maximum deflection case. Vertical direction deflection to a 1/2 of working height. Max. 20% loss of initial force. No technical function only to check the maximum lifetime. |
| Peeling Strength | 3 N | Test method according STR retention force of contact. (see 108-115061-1, in Figure 4) |
| Push Strength | 10 N Min. | Test method according STR peeling strength force of contact. (see 108-115061-1, in Figure 3) |

5.5 Product Qualification Test Sequence

| Test group | a | b | c | d | e | f | g | h | i | j | k | m | n |
|-------------------------------------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Sample size | 5 | 5 | 5 | 5 | 10 | 10 | 10 | 10 | 10 | 10 | 5 | 5 | 5 |
| Visual examination of product | 1,7 | 1,7 | 1,3 | 1,7 | 1,3 | 1,3 | 1,3 | 1,3 | 1,7 | 1,7 | 1,3 | 1,3 | 1,7 |
| Low level contact resistance | 2,6 | 2,6 | | 2,6 | | | | | 2,6 | 2,6 | | | 2,6 |
| Temperature rise | | | 2 | | | | | | | | | | |
| Damp heat | 4 | | | | | | | | | | | | |
| Vibration | | 4 | | | | | | | | | | | |
| Shock | | | | 4 | | | | | | | | | |
| Nitric Acid Vapour test | | | | | 2 | | | | | | | | |
| Solderability | | | | | | 2 | | | | | | | |
| Resistance to reflow soldering heat | | | | | | | 2 | | | | | | |
| Contact force | 3,5 | 3,5 | | 3,5 | | | | 2 | 3,5 | 3,5 | | | 3,5 |
| Durability (Life cycle) | | | | | | | | | 4 | | | | |
| Durability (Spring dynamic test) | | | | | | | | | | 4 | | | |
| Peeling Strength | | | | | | | | | | | 2 | | |
| Thermal Shock | | | | | | | | | | | | | 4 |
| Push Strength | | | | | | | | | | | | 2 | |

Numbers indicate sequence in which the tests are performed.

6. Test Result

| Group | Test Item | N | Condition | Test Result | | | Requirement | Judgment |
|-------|------------------------|---|-----------|---|----------|----------|---------------------------|----------|
| | | | | Max | Min | Ave | | |
| a | Examination of Product | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR | 5 | Initial | 45.16 mΩ | 42.32 mΩ | 43.47 mΩ | <75mΩ | Pass |
| | Contact Force | 5 | Initial | 0.28 N | 0.25 N | 0.27 N | 0.2N Min. at 1.4mm height | Pass |
| | | | | 1.18 N | 1.15 N | 1.17 N | 1.2N Max. at 0.8mm height | Pass |
| | Damp heat | 5 | Final | No physical damage occurred | | | No abnormalities | Pass |
| | Contact Force | 5 | Initial | 0.24 N | 0.22 N | 0.23 N | 0.2N Min. at 1.4mm height | Pass |
| | | | | 1.15 N | 1.10 N | 1.12 N | 1.2N Max. at 0.8mm height | Pass |
| | LLCR | 5 | Final | 45.32 mΩ | 43.12 mΩ | 44.32 mΩ | <100mΩ | Pass |
| | Examination of Product | 5 | Final | No physical damage occurred | | | No abnormalities | Pass |
| b | Examination of Product | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR | 5 | Initial | 44.85 mΩ | 43.10 mΩ | 44.10 mΩ | <75mΩ | Pass |
| | Vibration | 5 | Final | No discontinuities of 1 microsecond or longer duration occurred | | | No abnormalities | Pass |
| | LLCR | 5 | Final | 45.96 mΩ | 43.72 mΩ | 44.52 mΩ | <100mΩ | Pass |
| | Examination of Product | 5 | Final | No physical damage occurred | | | No abnormalities | Pass |
| c | Examination of Product | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Temperature rise | 5 | Final | 22.8°C | 19.15°C | 21.10°C | 30°C max. | Pass |
| | Examination of Product | 5 | Final | No physical damage occurred | | | No abnormalities | Pass |
| d | Examination of Product | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |

| | | | | | | | | |
|---|-------------------------------------|----|---------|---|----------|----------|---------------------------|------|
| | LLCR | 5 | Initial | 45.72 mΩ | 44.16 mΩ | 45.18 mΩ | <75mΩ | Pass |
| | Shock | 5 | Final | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR | 5 | Final | 45.78 mΩ | 43.91 mΩ | 44.65 mΩ | <100mΩ | Pass |
| | Examination of Product | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| e | Examination of Product | 10 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Nitric Acid Vapor Test | 10 | Final | No physical damage occurred | | | See Doc.11017-N-2.0. | Pass |
| | Examination of Product | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| f | Examination of Product | 10 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Solderability | 10 | Final | Soldering area have a minimum of 95% solder coverage. | | | 95% solder coverage | Pass |
| | Examination of Product | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| g | Examination of Product | 10 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Resistance to reflow soldering heat | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| | Examination of Product | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| h | Examination of Product | 10 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Contact force | 10 | Initial | 0.28N | 0.26N | 0.27N | 0.2N min. at 1.4mm height | Pass |
| | | | | 1.18N | 1.15N | 1.16N | 1.2N max. at 0.8mm height | Pass |
| | Examination of Product | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| i | Examination of Product | 10 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR | 10 | Initial | 44.10mΩ | 43.25 mΩ | 43.82 mΩ | <75mΩ | Pass |
| | Contact force | 10 | Initial | 0.29N | 0.26N | 0.27N | 0.2N min. at 1.4mm height | Pass |

| | | | | | | | | |
|---|---------------------------------|----|---------|-----------------------------|----------|----------|---------------------------|------|
| | | | | 1.18N | 1.15N | 1.16N | 1.2N max. at 0.8mm height | Pass |
| | Durability(5000 life cycle) | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| | Contact force | 10 | Final | 0.28N | 0.26N | 0.27N | 0.2N min. at 0.4mm height | Pass |
| | | | | 1.17N | 1.14N | 1.15N | 1.2N max. at 0.8mm height | Pass |
| | LLCR | 10 | Final | 45.20mΩ | 44.75 mΩ | 44.92 mΩ | <100 mΩ | Pass |
| | Examination of Product | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| j | Examination of Product | 10 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR | 10 | Initial | 44.92mΩ | 43.15 mΩ | 44.58 mΩ | <75mΩ | Pass |
| | Contact force | 10 | Initial | 0.29 N | 0.26 N | 0.27 N | 0.2N min. at 1.4mm height | Pass |
| | | | | 1.17 N | 1.13 N | 1.15 N | 1.2N max. at 0.8mm height | Pass |
| | Durability(spring dynamic test) | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| | Contact force | 10 | Final | 0.31 N | 0.27 N | 0.29 N | 0.2N min. at 1.4mm height | Pass |
| | | | | 1.18 N | 1.15 N | 1.17 N | 1.2N max. at 0.8mm height | Pass |
| | LLCR | 10 | Final | 45.30mΩ | 44.04 mΩ | 45.12 mΩ | <100mΩ | Pass |
| | Examination of Product | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| k | Examination of Product | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Peeling Strength | 5 | Initial | 19.5 N | 16.2 N | 18.3 N | 3N Min. | Pass |
| | Examination of Product | 5 | Final | No physical damage occurred | | | No abnormalities | Pass |
| m | Examination of Product | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Push Strength | 5 | Initial | 85.2 N | 76.3 N | 78.5 N | 10N Min. | Pass |

| | | | | | | | | |
|---|------------------------|---|---------|-----------------------------|----------|----------|---------------------------|------|
| | Examination of Product | 5 | Final | No physical damage occurred | | | No abnormal | Pass |
| n | Examination of Product | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR | 5 | Initial | 44.10 mΩ | 42.08 mΩ | 43.78 mΩ | <75mΩ | Pass |
| | Contact Force | 5 | Initial | 0.28 N | 0.25 N | 0.26 N | 0.2N min. at 1.4mm height | Pass |
| | | | | 1.17 N | 1.15 N | 1.16 N | 1.2N max. at 0.8mm height | Pass |
| | Thermal Shock | 5 | Final | No physical damage occurred | | | No abnormalities | Pass |
| | Contact Force | 5 | Final | 0.23 N | 0.22 N | 0.22 N | 0.2N min. at 1.4mm height | Pass |
| | | | | 1.16 N | 1.12 N | 1.13 N | 1.2N max. at 0.8mm height | Pass |
| | LLCR | 5 | Final | 44.26 mΩ | 43.15 mΩ | 43.68 mΩ | <100mΩ | Pass |
| | Examination of Product | 5 | Final | No physical damage occurred | | | No abnormal | Pass |

END